

# 2SK1151(L)(S), 2SK1152(L)(S)

Silicon N-Channel MOS FET

# HITACHI

## Application

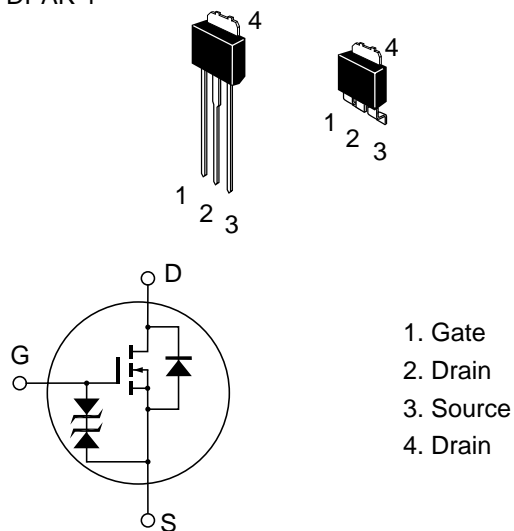
High speed power switching

## Features

- Low on-resistance
- High speed switching
- Low drive current
- No secondary breakdown
- Suitable for switching regulator and DC-DC converter

## Outline

DPAK-1



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## 2SK1151(L)(S), 2SK1152(L)(S)

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### Absolute Maximum Ratings (Ta = 25°C)

Item		Symbol	Ratings	Unit
Drain to source voltage	2SK1151	$V_{DSS}$	450	V
	2SK1152		500	
Gate to source voltage		$V_{GSS}$	±30	V
Drain current		$I_D$	1.5	A
Drain peak current		$I_{D(pulse)}$ <sup>*1</sup>	6	A
Body to drain diode reverse drain current		$I_{DR}$	1.5	A
Channel dissipation		$P_{ch}$ <sup>*2</sup>	20	W
Channel temperature		Tch	150	°C
Storage temperature		Tstg	-55 to +150	°C

Notes: 1.  $PW \leq 10 \mu s$ , duty cycle  $\leq 1\%$

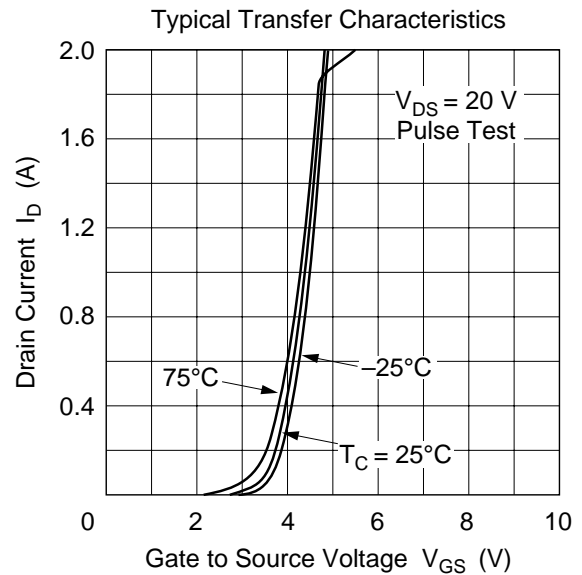
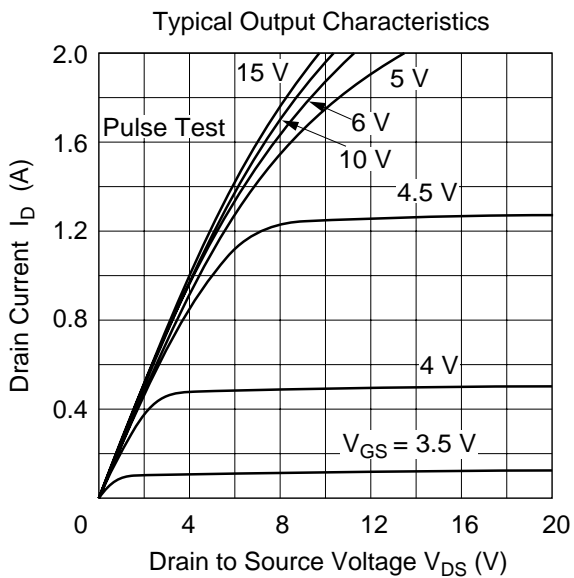
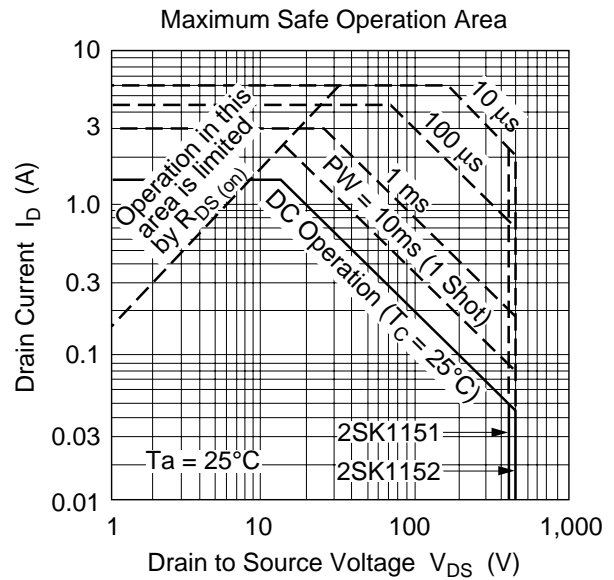
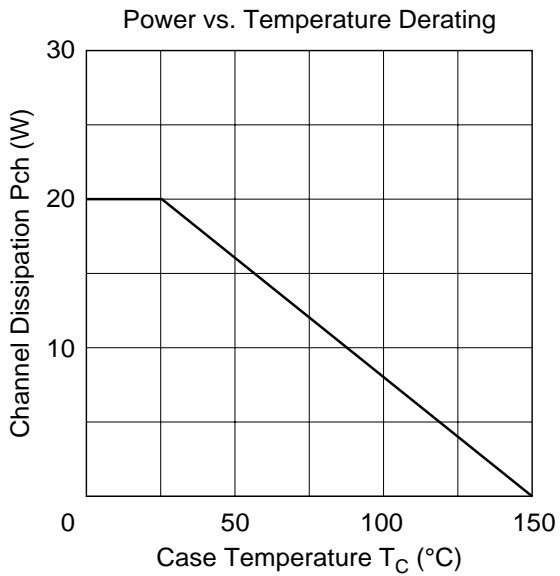
2. Value at  $T_C = 25^\circ C$

**Electrical Characteristics (Ta = 25°C)**

Item		Symbol	Min	Typ	Max	Unit	Test conditions
Drain to source breakdown voltage	2SK1151 2SK1152	$V_{(BR)DSS}$	450 500	—	—	V	$I_D = 10 \text{ mA}, V_{GS} = 0$
Gate to source breakdown voltage		$V_{(BR)GSS}$	±30	—	—	V	$I_G = \pm 100 \mu\text{A}, V_{DS} = 0$
Gate to source leak current		$I_{GSS}$	—	—	±10	μA	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0$
Zero gate voltage drain current	2SK1151 2SK1152	$I_{DSS}$	—	—	100	μA	$V_{DS} = 360 \text{ V}, V_{GS} = 0$ $V_{DS} = 400 \text{ V}, V_{GS} = 0$
Gate to source cutoff voltage		$V_{GS(off)}$	2.0	—	3.0	V	$I_D = 1 \text{ mA}, V_{DS} = 10 \text{ V}$
Static Drain to source on state resistance	2SK1151 2SK1152	$R_{DS(on)}$	—	3.5 4.0	5.5 6.0	Ω	$I_D = 1 \text{ A}, V_{GS} = 10 \text{ V}^{*1}$
Forward transfer admittance		yfs	0.6	1.1	—	S	$I_D = 1 \text{ A}, V_{DS} = 20 \text{ V}^{*1}$
Input capacitance		Ciss	—	160	—	pF	$V_{DS} = 10 \text{ V}, V_{GS} = 0,$
Output capacitance		Coss	—	45	—	pF	f = 1 MHz
Reverse transfer capacitance		Crss	—	5	—	pF	
Turn-on delay time		$t_{d(on)}$	—	5	—	ns	$I_D = 1 \text{ A}, V_{GS} = 10 \text{ V},$
Rise time		$t_r$	—	10	—	ns	$R_L = 30 \Omega$
Turn-off delay time		$t_{d(off)}$	—	20	—	ns	
Fall time		$t_f$	—	10	—	ns	
Body to drain diode forward voltage		$V_{DF}$	—	1.0	—	V	$I_F = 1.5 \text{ A}, V_{GS} = 0$
Body to drain diode reverse recovery time		$t_{rr}$	—	220	—	ns	$I_F = 1.5 \text{ A}, V_{GS} = 0,$ $di_F/dt = 100 \text{ A}/\mu\text{s}$

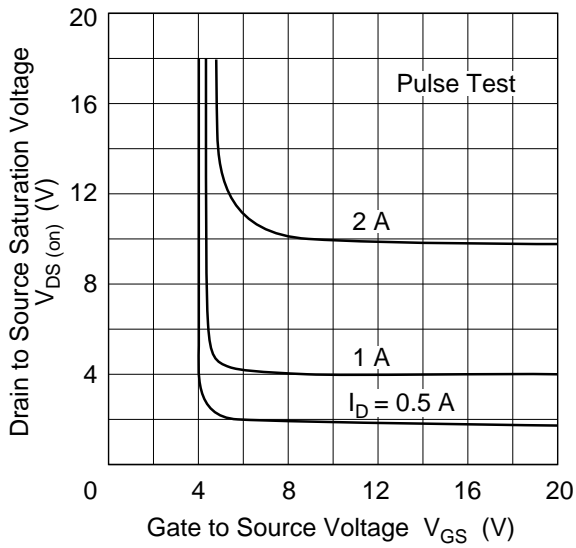
Note: 1. Pulse test

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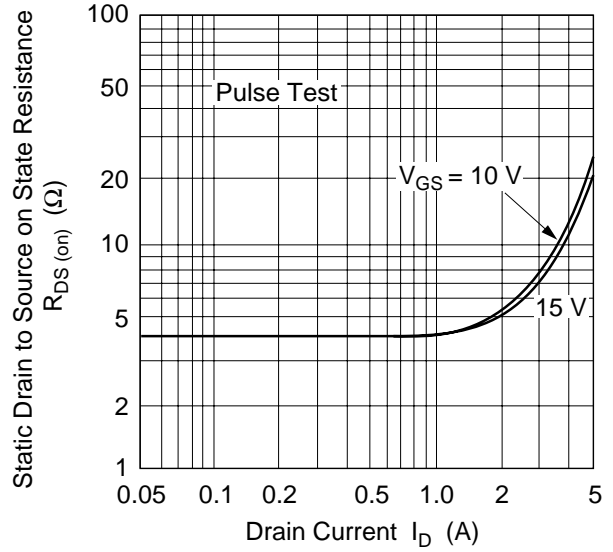


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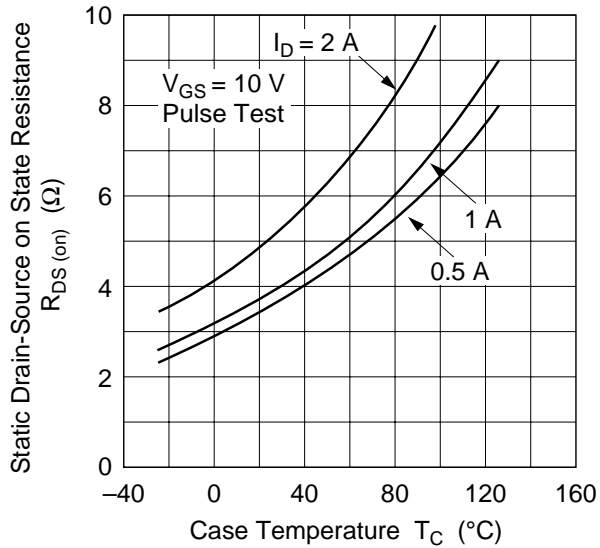
Drain to Source Saturation Voltage vs. Gate to Source Voltage



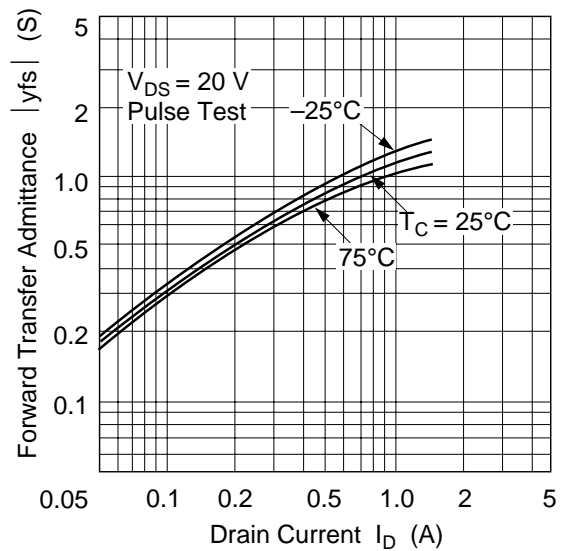
Static Drain to Source on State Resistance vs. Drain Current



Static Drain to Source on State Resistance vs. Temperature

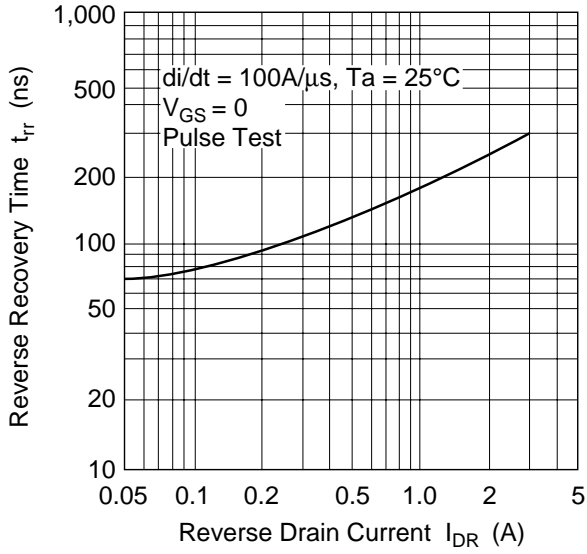


Forward Transfer Admittance vs. Drain Current

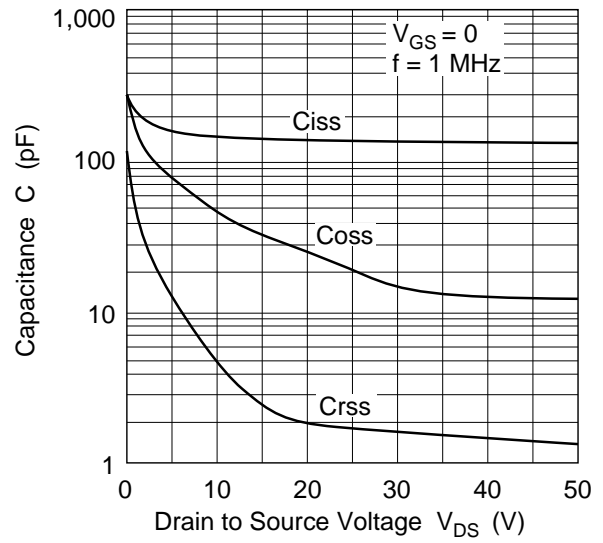


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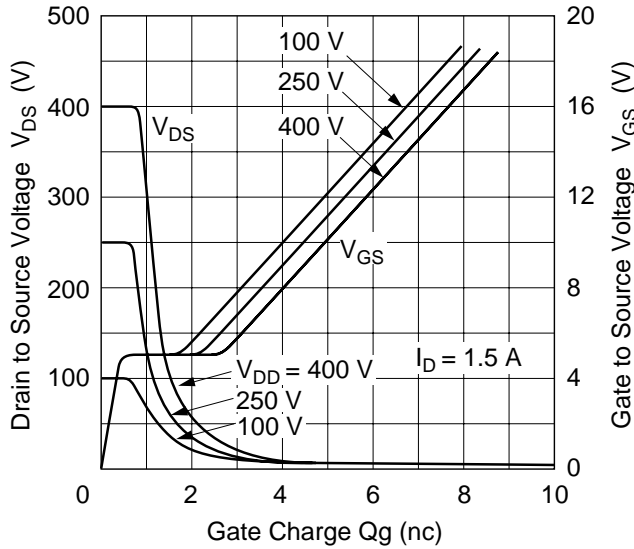
Body to Drain Diode Reverse Recovery Time



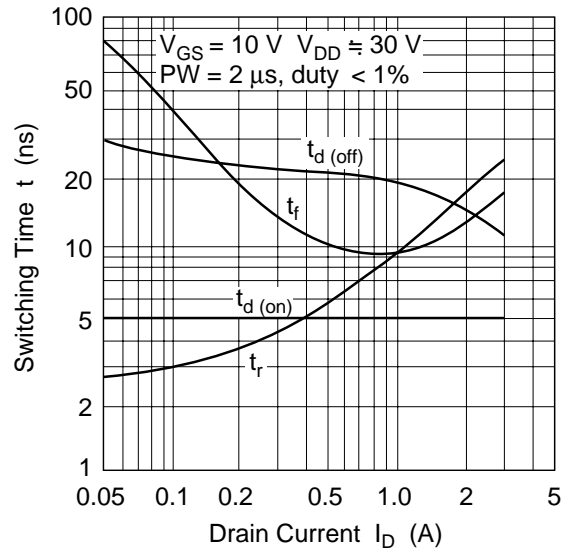
Typical Capacitance vs. Drain to Source Voltage

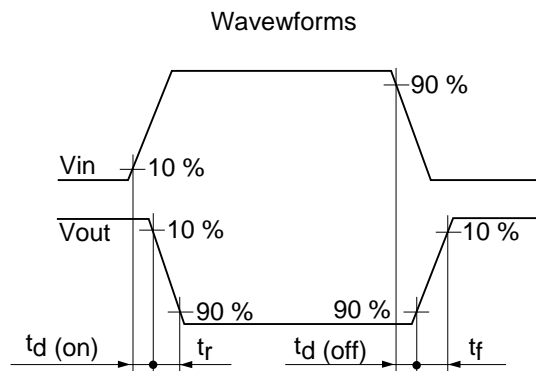
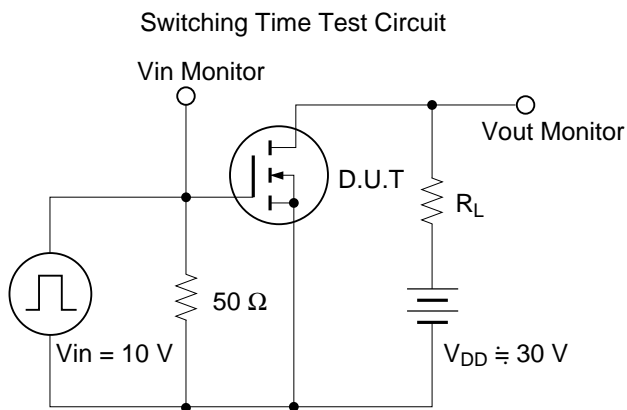
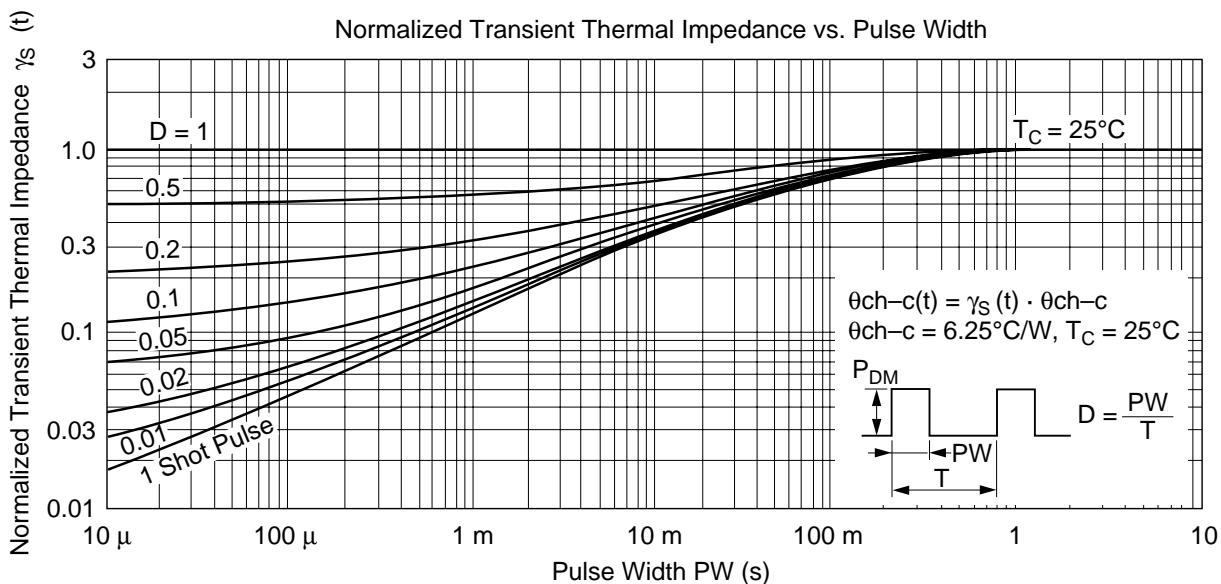
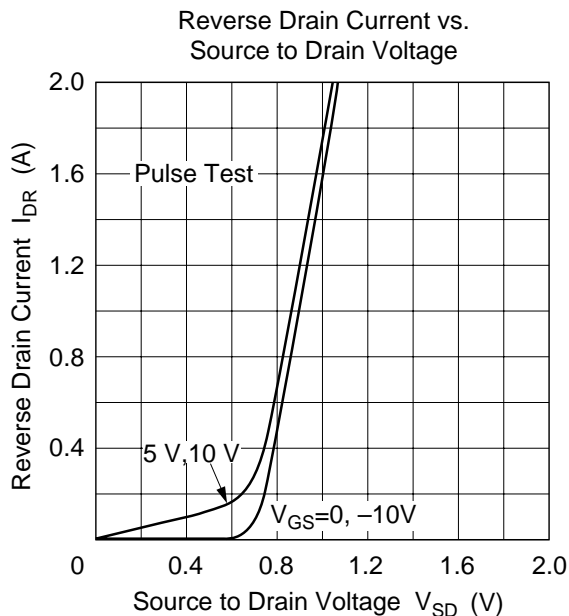


Dynamic Input Characteristics

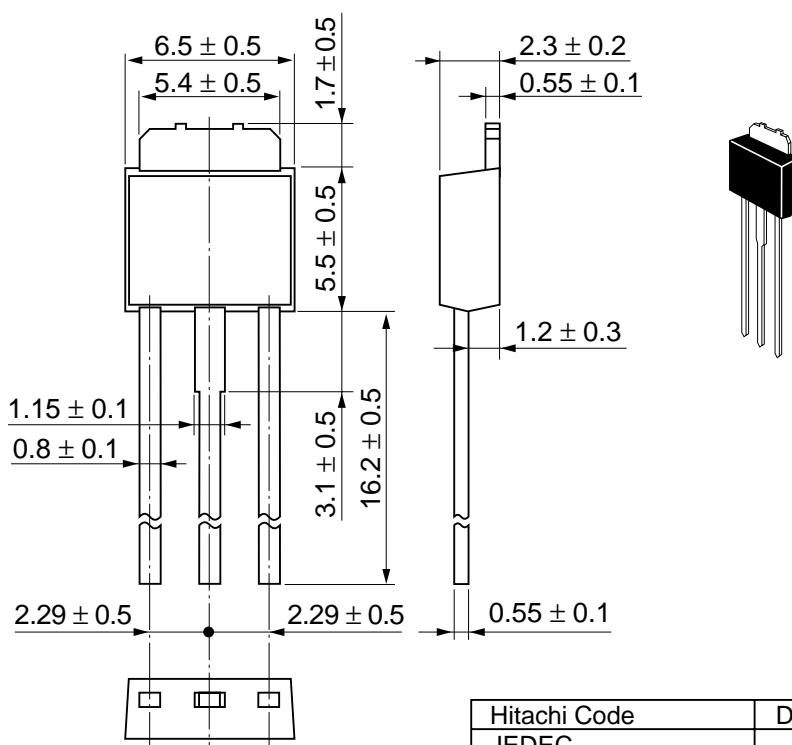


Switching Characteristics





Unit: mm



Hitachi Code	DPAK (L)-(1)
JEDEC	—
EIAJ	Conforms
Weight (reference value)	0.42 g



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